

Technical information : ULTRA SOFT THERMAL INTERFACES

Description:

A thermal interface material transfers heat from a hot to a cold point. It removes the air zones between the hot surface and the heatsink. Ultra Soft thermal interfaces are made of a polymer matrix charges with thermal conductive particles. The Ultra Soft Thermal Interfaces are very conformable to adapt themselves to component's reliefs on a PCB.

Material	Silicone base
Hardness	<25 Shore 00
Conductivity	≤17 W/m.k
Available charges	Boron nitrite, aluminum oxide, zinc oxide, aluminum or silver...
Packaging	In sheets or custom cut according to your drawings

Properties		Unit	T006P	T011P	T013P	Test method
Physical Properties	Specific gravity	-		3.4	3.3	ASTM D792
	Hardness	Shore 00	Low Modulus			ASTM D2240
Electrical Properties	Volume Resistivity	Ohm-m	1.0 x 10 ¹⁶	1.0 x 10 ¹⁰	1.0 x 10 ¹¹	ASTM D257
	Breakdown Voltage	kV/mm (Volts/mil)		11 (279)	12 (305)	ASTM D149
	Dielectric Strength	kV/mm (Volts/mil)	N/A			ASTM D149
	Dielectric Constant	50Hz / 1kHz / 1MHz		8.58 / 8.33 / 7.77	9.28 / 8.58 / 7.76	ASTM D150
	Dissipation Factor	50 Hz / 1kHz / 1MHz		0.0245 / 0.0172 / 0.0114	0.0483 / 0.0389 / 0.0147	ASTM D150
Thermal Properties	Thermal Conductivity	W/m.K	6.0	11.0	13.0	ASTM D5470
	Useful temperature	°C (°F)	-40 to +150 (-40 to +302)			-
	Low Molecular Siloxane	Wt %		0.0014 or less	0.0158 or less	Gas Chromatography
	Flame Retardant	UL94	V0			UL94